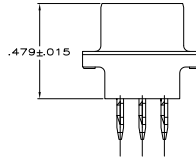
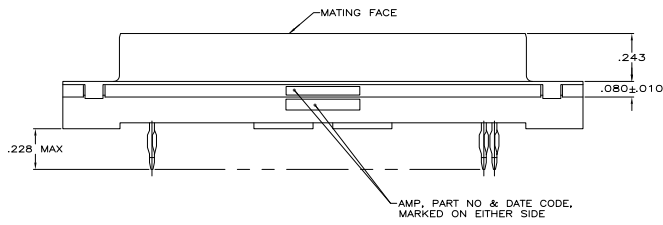
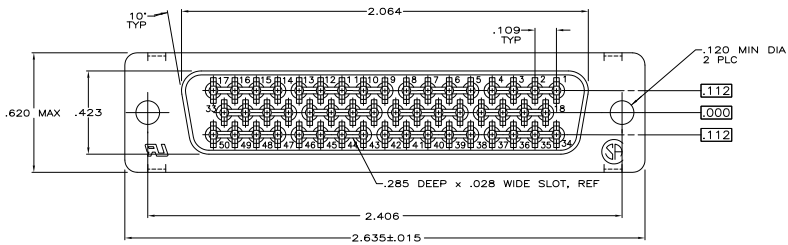


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REV	DATE	DESCRIPTION	BY	APP'D
00				
H		REVISED PER EDD-12-00090		



- △ FOR USE WITH .093 MINIMUM THICK PRINTED CIRCUIT BOARD. REFER TO APPLICATION SPECIFICATION FOR PRINTED CIRCUIT BOARD LAYOUT DIMENSIONS AND FINISH RECOMMENDATIONS.
- △ DUPLEX PLATED: GOLD FLASH ON MATING SURFACE, BRIGHT TIN OR BRIGHT TIN LEAD ON COMPLIANT PIN, ALL OVER NICKEL.
- △ .00030 MINIMUM GOLD IN MATING AREA.
 .000100 MINIMUM TIN OR TIN-LEAD ON COMPLIANT PIN, ALL OVER .000050 MINIMUM NICKEL.
 OR
 GOLD FLASH OVER PALLADIUM NICKEL.
 .00030 MINIMUM TOTAL IN MATING AREA.
 .000100 MINIMUM TIN OR TIN-LEAD ON COMPLIANT PIN, ALL OVER .000050 MINIMUM NICKEL.
- △ PLATED .0002-.0004 BRIGHT TIN

SUPERSEDED BY 747143-2	747143-2
	747143-1
CONTACT FINISH	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT. ENGINEERING AND TELEMARKETING PER AMPLITE 114-40014		DATE: 04-12-94	REVISED: 04-28-94	TE Connectivity
DESCRIPTION: 108-40014	PROJECT: 114-40026	DATE: 04-12-94	REVISED: 04-28-94	RCPT ASSY, SIZE 0, 50 POSN, AMPLITE™ HDP, MOM PROFILE, W/ ACTION PIN CONT & METAL SHELL
REVISED: 114-40026	DATE: 04-28-94	REVISED: 04-28-94	REVISED: 04-28-94	REVISED: 04-28-94
CUSTOMER DRAWING	DATE: 04-28-94	REVISED: 04-28-94	REVISED: 04-28-94	REVISED: 04-28-94